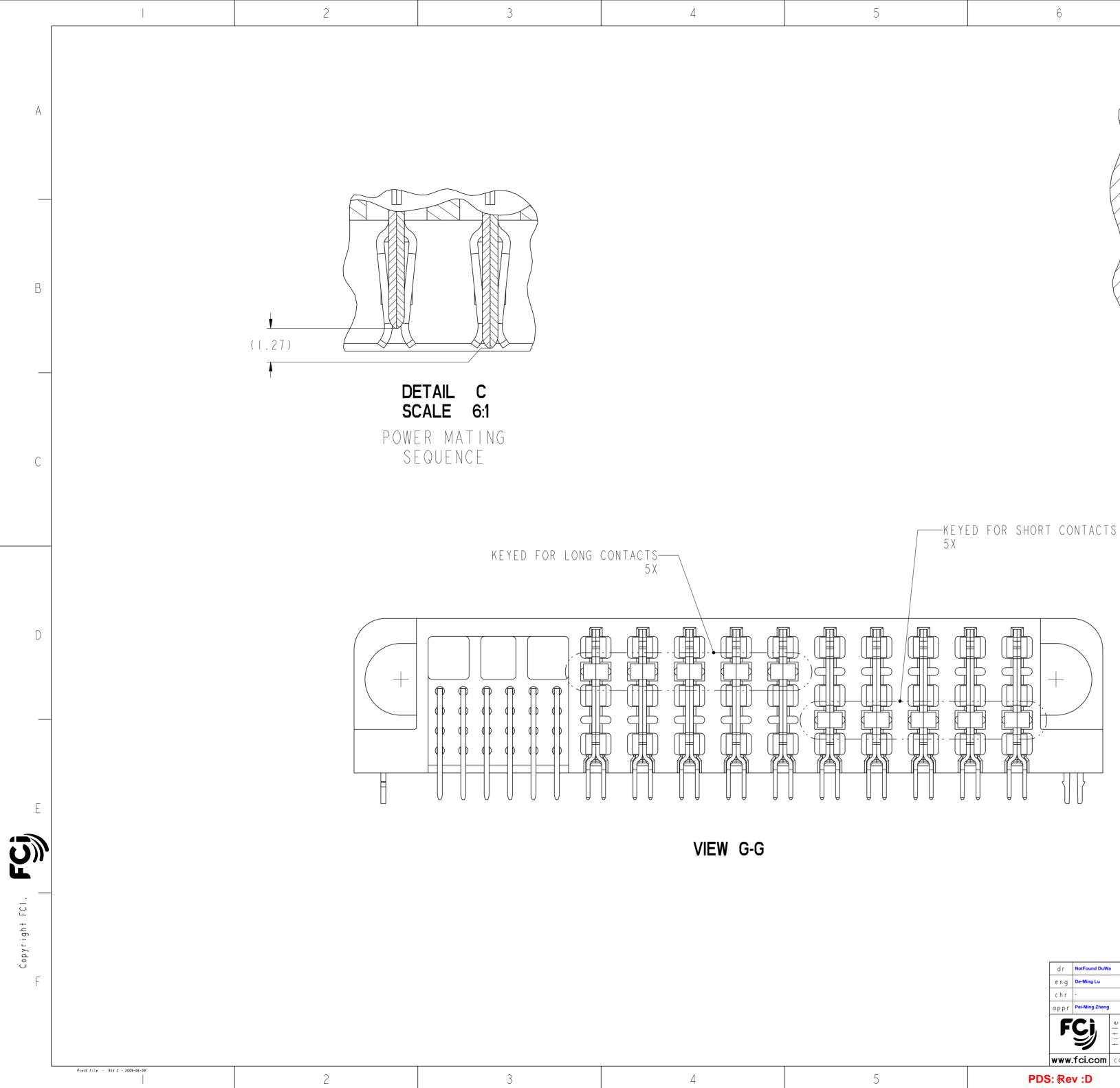
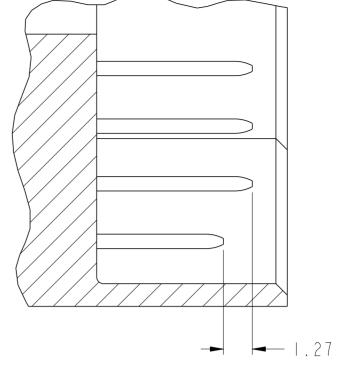


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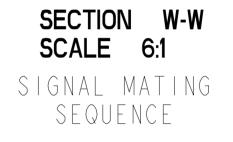
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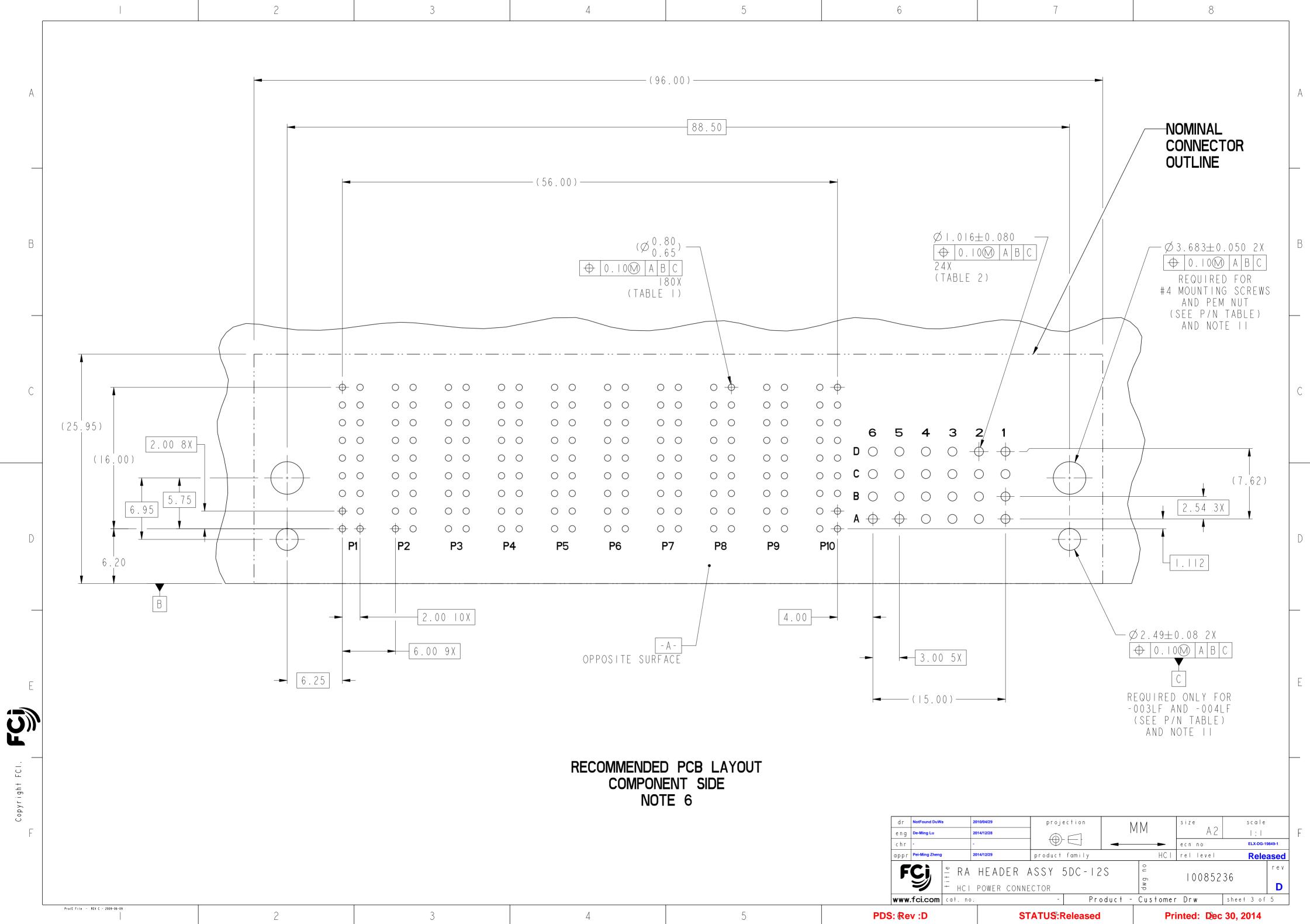
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TOP LAYER			PLAT	TABLE I (HCI ED THROUGH-HOLE				
DESCRIPTION	DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	NICKEL THICKNESS	GOLD THICKNESS	T I N THICKNESS	SILVER THICKNESS	FINISHED HOLE DIAMETER
TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015					0.65 - 0.80
IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050				0.9 - I.5um		0.70 - 0.80
		0.025 - 0.050					0.15 - 0.65um	0.70 - 0.80
IMMERSION SILVER	0.81-0.86 (0.85 DRILL)	0.025 0.050						
		0.025 - 0.050						0.70 - 0.80
				0.003 - 0.007	 Flash up to 0.0002			0.70 - 0.80 0.69 - 0.80
COPPER (SEE NOTE 9) GOLD TOP LAYER	0.81-0.86 (0.85 DRILL)	0.025 - 0.050			FLASH UP TO 0.0002			
COPPER (SEE NOTE 9) GOLD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050		0.003 - 0.007 TABLE 2 (HPC S	FLASH UP TO 0.0002			0.69 - 0.80 FINISHED
COPPER (SEE NOTE 9) GOLD TOP LAYER	0.81-0.86 (0.85 DRILL) 0.81-0.86 (0.85 DRILL) DRILLED HOLE	0.025 - 0.050 0.025 - 0.050 COPPER	 P L A T T I N - L E A D	O.003 - O.007 TABLE 2 (HPC S ED THROUGH-HOLE NICKEL	FLASH UP TO 0.0002 IGNALS) REQUIREMENTS GOLD	 T I N	 SILVER	0.69 - 0.80 FINISHED HOLE DIAMETER 0.94 - 1.10
COPPER (SEE NOTE 9) GOLD TOP LAYER DESCRIPTION	0.81-0.86 (0.85 DRILL) 0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER 1.125-1.175	0.025 - 0.050 0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS	O.003 - O.007 TABLE 2 (HPC S ED THROUGH-HOLE NICKEL THICKNESS	FLASH UP TO 0.0002 IGNALS) REQUIREMENTS GOLD THICKNESS	 T I N T H I C K N E S S	SILVER THICKNESS	0.69 - 0.80 FINISHED HOLE DIAMETER 0.94 - 1.10
COPPER (SEE NOTE 9) GOLD TOP LAYER DESCRIPTION TIN-LEAD	0.81-0.86 (0.85 DRILL) 0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER 1.125-1.175	0.025 - 0.050 0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS 0.005-0.015	O.003 - O.007 TABLE 2 (HPC S ED THROUGH-HOLE NICKEL THICKNESS 	FLASH UP TO 0.0002 IGNALS) REQUIREMENTS GOLD THICKNESS 	 T I N T H I C K N E S S	SILVER THICKNESS 	0.69 - 0.80 FINISHED HOLE DIAMETER 0.94 - 1.10
COPPER (SEE NOTE 9) GOLD TOP LAYER DESCRIPTION TIN-LEAD IMMERSION TIN	0.81-0.86 (0.85 DRILL) 0.81-0.86 (0.85 DRILL) DRILLED HOLE DIAMETER I.125-1.175 (Ø.0453±.0010)	0.025 - 0.050 0.025 - 0.050 COPPER THICKNESS	 PLAT TIN-LEAD THICKNESS 0.005-0.015 	0.003 - 0.007 TABLE 2 (HPC S ED THROUGH-HOLE NICKEL THICKNESS 	FLASH UP TO 0.0002 IGNALS) REQUIREMENTS GOLD THICKNESS 	 TIN THICKNESS 	SILVER THICKNESS 	0.69 - 0.80 FINISHED HOLE DIAMETER

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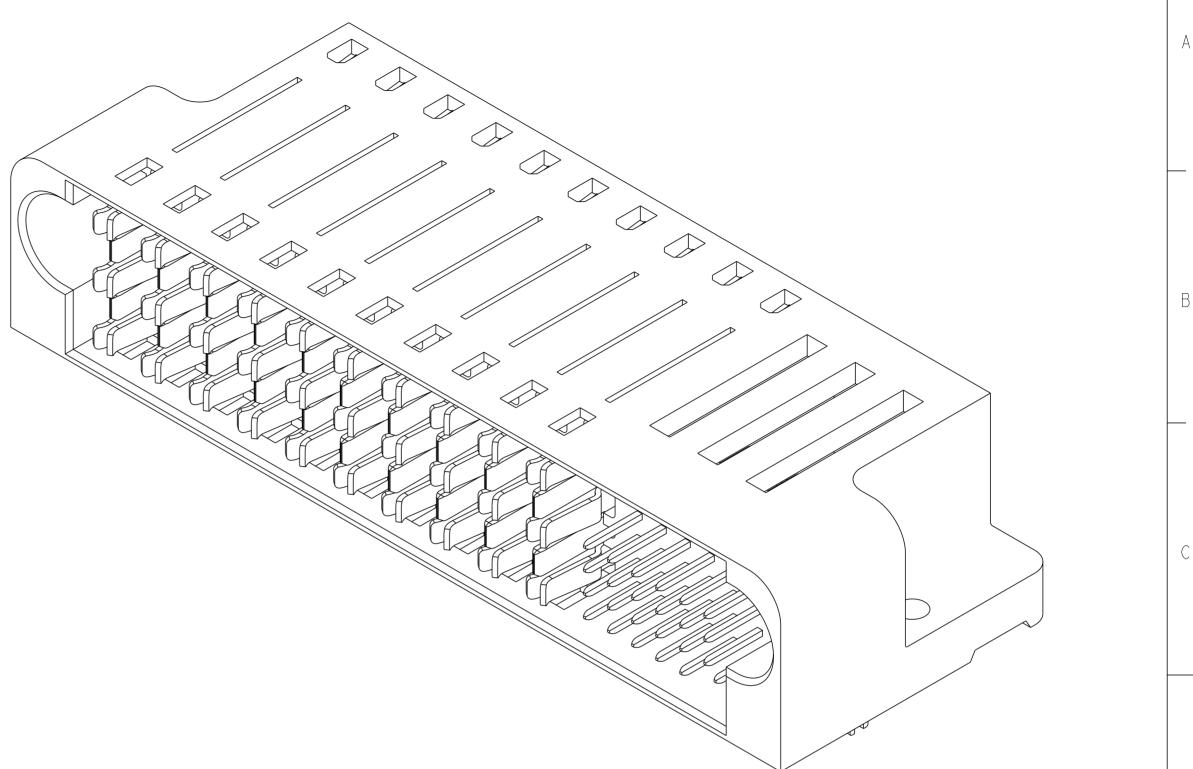
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	PART NUMBER	RETENTION CLIPS	#4 SCREW	DIM A ±0.25 (TAIL LENGTH)	TAIL TYPE	I			· · ·	
	10085236-001LF	NO	YES	3.43	SOLDER TAIL					
	10085236-002LF	NO	YES	4.70	SOLDER TAIL					
٨	10085236-003LF	YES	NO	3.43	SOLDER TAIL		\wedge			
	10085236-004LF	YES	NO	4.70	SOLDER TAIL					



NOTES:

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Pro/E File - REV C - 2009-06-09

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- I. CONNECTOR MATERIALS: HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK UL 94V-0 COMPLIANT CONTACTS: HIGH PERFORMANCE COPPER ALLOY
- 2. CONTACT FINISH (ref GS-12-380 SECTION 5.2)
- 3. PRODUCT SPECIFICATION: GS-12-380. (IN PROGRESS)
- 4. APPLICATION SPECIFICATION: GS-20-070. (IN PROGRESS)
- (5.) product marking (product number & date code) on housing in area shown.
- (6.) MINIMUM NOMINAL PCB THICKNESS: I.6mm
- 7. PACKAGING MEETS FCI SPECIFICATION GS-14-1073.
- (8.) HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
- 9. COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
- IO. ALL HOLE SIZES ARE FINISHED HOLE SIZES.
- (II) MOUNTING HOLES ARE UNPLATED.

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